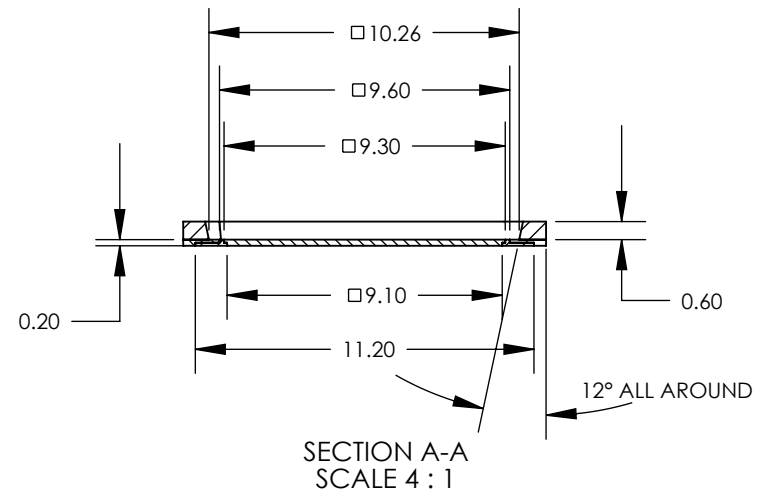
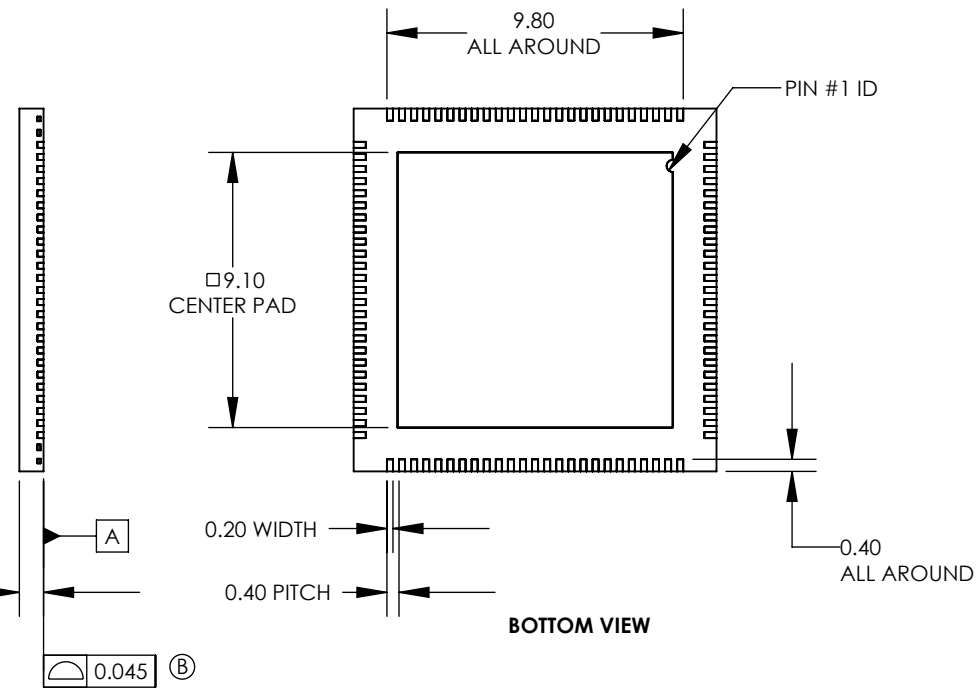
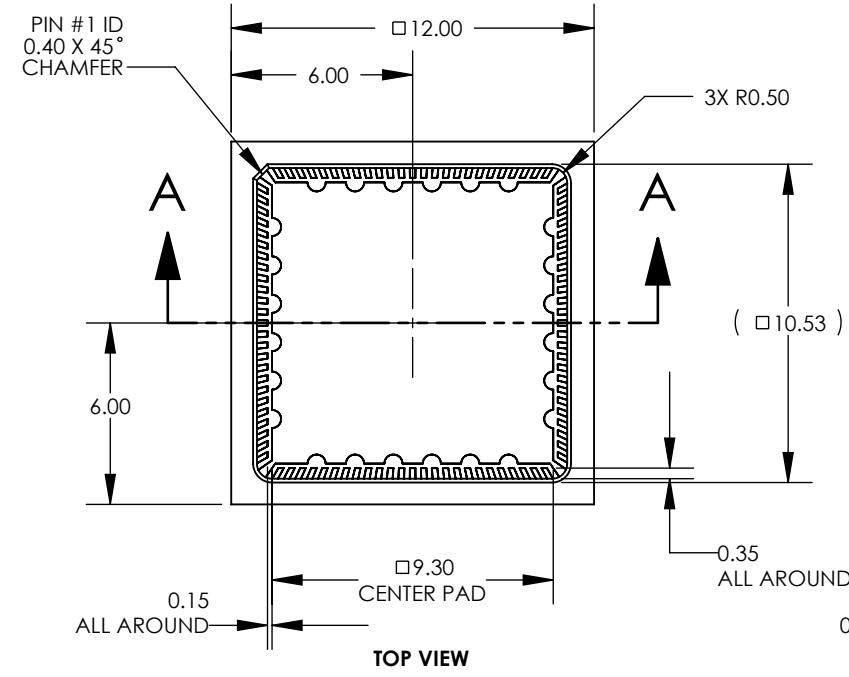


8 7 6 5 4 3 2 1

REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	8/11/11	SS
B5	B	.045 PROFILE LIMIT WAS .05	5/16/2017	SS

D
C
B
A

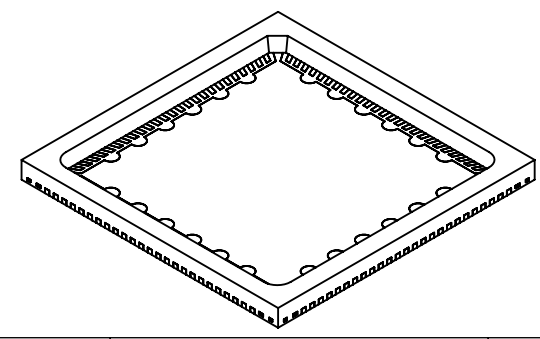
D
C
B
A



NOTES:

- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (2.5µm-7.6µm) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1µm-2µm) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

0.045 (B)



**OPEN·molded
Plastic Package**



PROPRIETARY AND CONFIDENTIAL
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .XX: ±0.25		NAME	DATE	 TITLE: QP-QFN100-12MM-0.40MM		
		DRAWN	D. Abbe	8/11/11				
		CHECKED	S. Swen	8/11/11				
		ENG APPR.	S. Swen	8/11/11		SIZE B	DWG. NO. 500412	REV B
		COMMENTS:			SCALE: 6:1			
NEXT ASSY	USED ON	MATERIAL	SEE NOTE 1					
		FINISH	SEE NOTE 2					
APPLICATION		DO NOT SCALE DRAWING						

8 7 6 5 4 3 2 1